

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **WILLIAM HONG, CHIA-CHE CHUANG, CHI-WEI CHUNG, WEN-CHIH CHIOU, YING-HO CHEN, SYUN-MING JANG**

For: **COPPER CMP DEFECT REDUCTION BY EXTRA SLURRY POLISH**

Enclosed are:

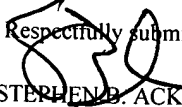
- ☒ **4** sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Taiwan Semiconductor Manufacturing Co.**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b)(2)(b)(i)

03945 U.S. PTO
10/714985
111703

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 770.
TOTAL CLAIMS	19 -20=	0	x 18 =	\$ 0.
INDEP CLAIMS	2 -3=	0	x 86 =	\$ 0.
SUB TOTAL				\$ 770.
ASSIGNMENT				\$40.
TOTAL				\$ 810.

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- ☒ Any additional filing fees required under 37 CFR §1.16.
- ☒ Any patent application processing fees under 37 CFR §1.17.

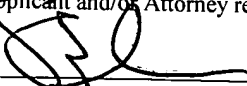
Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

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Express Mail No. **EV313927410US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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